



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD50N06S2L-13	Issued	13. May 2021
MA#	MA001883208		
Package	PG-TO252-3-11	Weight*	372.20 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.029	1.08	1.08	10824	10824
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		578	
	non noble metal	copper	7440-50-8	215.017	57.77	57.85	577691	578443
wire	non noble metal	aluminium	7429-90-5	2.898	0.78	0.78	7787	7787
encapsulation	inorganic material	zinc oxide	1314-13-2	1.237	0.33		3324	
	miscellaneous	miscellaneous	-	6.186	1.66		16619	
	plastics	epoxy resin	-	18.557	4.99		49857	
	inorganic material	silicon dioxide	60676-86-0	97.733	26.26	33.24	262582	332382
lead finish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10048	10048
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.065	0.02		174	
	noble metal	silver	7440-22-4	0.081	0.02		217	
	non noble metal	lead	7439-92-1	3.085	0.83	0.87	8288	8679
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.15	5.16	51525	51592
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com